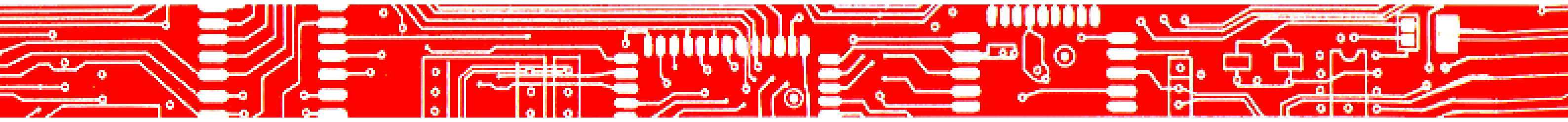

SMT ADHESIVE – Heat Cure Type
JU – 44P

Features

1) Ensure good printability
2) High slump resistivity.
3) Very high bonding stringth.
4) Long shelf life.

Curing condition

120 °C x > 90 sec.
130 ~ 150 °C x > 60 sec.

Specifications

Product			**JU – 44P**
Bonding strength	Application		Printing
	Composition		Epoxy
	State * Color		Paste * Red
	Specific gravity		1.22 ± 0.05
	Viscosity (Pa.s * 20ºC)		70 ± 10
	Thixotropy (20ºC)		3.5 ± 0.5
	Non-volatile (105ºC * 3hr)		> 99%
	Shelf life	At room temp. (20ºC)	3 months
		Below 10ºC	6 months
After curing	State * Color		Polymer * dark red
	Bonding strength	2125 square chip	> 3 kg
		Minimold Tr	> 3 kg
	Copper plate corrosion (40ºC 90%RH72hr)		Passed
	Heat resistivity (250ºC x 10sec.)		Passed
	Surface insulation resistance	Initial value (Ω)	> 1x 10^{12}
		40ºC, 95%RH x 96hr (Ω)	> 1x 10^{11}
	Water absorption (%)		0,1 %
	Dielectric constant (1 MHz)		3.4
	Dielectric tangent (1 MHz)		0.016

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